Preferred Device

Sensitive Gate Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed and tested for repetitive peak operation required for CD ignition, fuel ignitors, flash circuits, motor controls and low-power switching applications.

- 150 Amperes for 2 µs Safe Area
- High dv/dt
- Very Low Forward "On" Voltage at High Current
- Low-Cost TO-226AA (TO-92)
- Device Marking: Device Type, e.g., MCR22-6, Date Code

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (R _{GK} = IK, T _J = - 40 to +110°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR22-6 MCR22-8	VDRM, VRRM	400 600	Volts
On-State Current RMS (180° Conduction Angles, T _C = 80°C)	IT(RMS)	1.5	Amps
Peak Non-repetitive Surge Current, T _A = 25°C (1/2 Cycle, Sine Wave, 60 Hz)	ITSM	15	Amps
Circuit Fusing Considerations (t = 8.3 ms)	I ² t	0.9	A ² s
Forward Peak Gate Power (Pulse Width ≤ 1.0 μsec, T _A = 25°C)	Рдм	0.5	Watt
Forward Average Gate Power (t = 8.3 msec, T _A = 25°C)	P _G (AV)	0.1	Watt
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T _A = 25°C)	I _{FGM}	0.2	Amp
Reverse Peak Gate Voltage (Pulse Width ≤ 1.0 μs, T _A = 25°C)	^V RGM	5.0	Volts
Operating Junction Temperature Range @ Rated V _{RRM} and V _{DRM}	TJ	-40 to +110	°C
Storage Temperature Range	T _{stg}	–40 to +150	°C

(1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



ON Semiconductor

http://onsemi.com

SCRs 1.5 AMPERES RMS 400 thru 600 VOLTS





TO-92 (TO-226AA) CASE 029 STYLE 10

PIN ASSIGNMENT		
1	Cathode	
2	Gate	
3	Anode	

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{ heta JC}$	50	°C/W
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	160	°C/W
Lead Solder Temperature (Lead Length ≥ 1/16" from case, 10 s Max)	TL	+260	°C

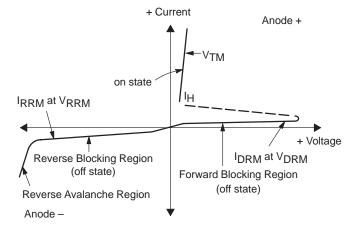
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Peak Repetitive Forward or Reverse Blocking Current (VAK = Rated VDRM or VRRM; RGK = 1000 Ohms) $T_{C} = 25^{\circ}C$ $T_{C} = 110^{\circ}C$		I _{DRM} , I _{RRM}	_	_	10 200	μA μA
ON CHARACTERISTICS		-		-		
Peak Forward On–State Voltage(1) (I _{TM} = 1 A Peak)		V _{TM}	_	1.2	1.7	Volts
Gate Trigger Current (Continuous dc) ⁽²⁾ (V _{AK} = 6 Vdc, R _L = 100 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	lGT	_	30 —	200 500	μА
Gate Trigger Voltage (Continuous dc) $^{(2)}$ (VAK = 7 Vdc, RL = 100 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	VGT	_	_	0.8 1.2	Volts
Gate Non-Trigger Voltage ⁽¹⁾ (V _{AK} = 12 Vdc, R _L = 100 Ohms)	T _C = 110°C	V _{GD}	0.1	_	_	Volts
		lн		2.0 —	5.0 10	mA
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of Off–State Voltage (T _C = 110°C)		dv/dt	_	25	_	V/μs

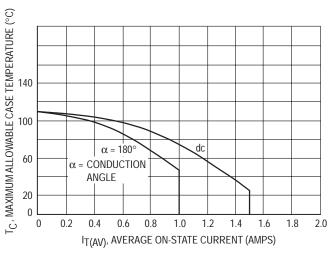
⁽¹⁾ Pulse Width = 1.0 ms, Duty Cycle ≤ 1%.(2) R_{GK} Current not included in measurement.

Voltage Current Characteristic of SCR

Symbol	Parameter
V _{DRM}	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
VTM	Peak on State Voltage
I⊔	Holding Current



CURRENT DERATING





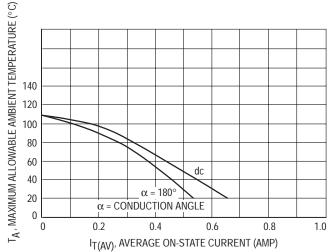


Figure 2. Maximum Ambient Temperature

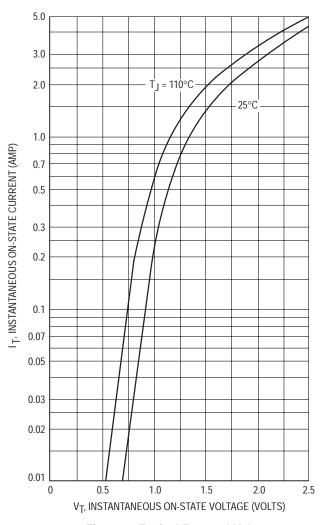


Figure 3. Typical Forward Voltage

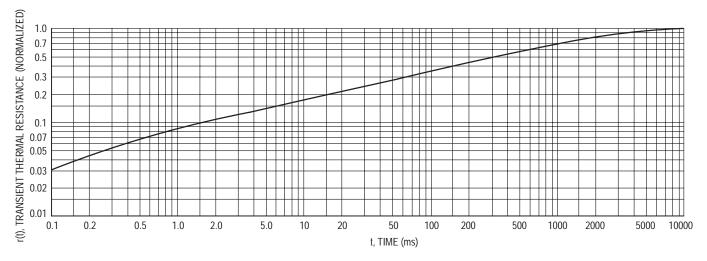


Figure 4. Thermal Response

TYPICAL CHARACTERISTICS

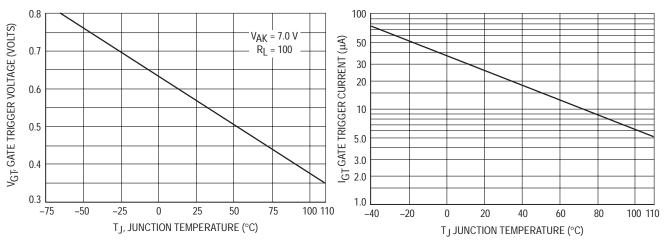


Figure 5. Typical Gate Trigger Voltage

Figure 6. Typical Gate Trigger Current

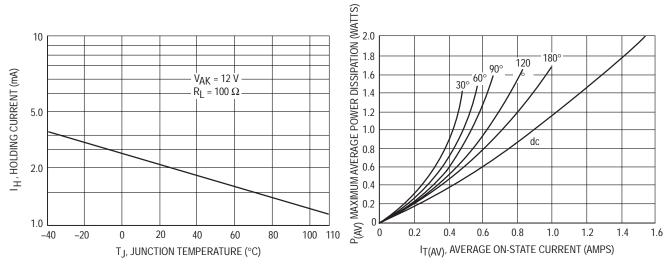


Figure 7. Typical Holding Current

Figure 8. Power Dissipation

TO-92 EIA RADIAL TAPE IN FAN FOLD BOX OR ON REEL

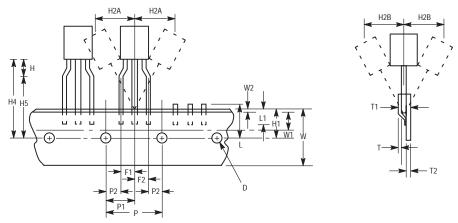


Figure 9. Device Positioning on Tape

		Specification				
			Inches		Millimeter	
Symbol	Item	Min	Max	Min	Max	
D	Tape Feedhole Diameter	0.1496	0.1653	3.8	4.2	
D2	Component Lead Thickness Dimension	0.015	0.020	0.38	0.51	
F1, F2	Component Lead Pitch	0.0945	0.110	2.4	2.8	
Н	Bottom of Component to Seating Plane	.059	.156	1.5	4.0	
H1	Feedhole Location	0.3346	0.3741	8.5	9.5	
H2A	Deflection Left or Right	0	0.039	0	1.0	
H2B	Deflection Front or Rear	0	0.051	0	1.0	
H4	Feedhole to Bottom of Component	0.7086	0.768	18	19.5	
H5	Feedhole to Seating Plane	0.610	0.649	15.5	16.5	
L	Defective Unit Clipped Dimension	0.3346	0.433	8.5	11	
L1	Lead Wire Enclosure	0.09842	_	2.5	_	
Р	Feedhole Pitch	0.4921	0.5079	12.5	12.9	
P1	Feedhole Center to Center Lead	0.2342	0.2658	5.95	6.75	
P2	First Lead Spacing Dimension	0.1397	0.1556	3.55	3.95	
Т	Adhesive Tape Thickness	0.06	0.08	0.15	0.20	
T1	Overall Taped Package Thickness	_	0.0567	_	1.44	
T2	Carrier Strip Thickness	0.014	0.027	0.35	0.65	
W	Carrier Strip Width	0.6889	0.7481	17.5	19	
W1	Adhesive Tape Width	0.2165	0.2841	5.5	6.3	
W2	Adhesive Tape Position	.0059	0.01968	.15	0.5	

NOTES:

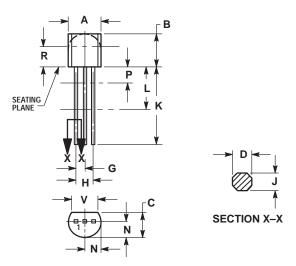
- 1. Maximum alignment deviation between leads not to be greater than 0.2 mm.
- 2. Defective components shall be clipped from the carrier tape such that the remaining protrusion (L) does not exceed a maximum of 11 mm.
- 3. Component lead to tape adhesion must meet the pull test requirements.
- 4. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
- 5. Holddown tape not to extend beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
- 6. No more than 1 consecutive missing component is permitted.
- 7. A tape trailer and leader, having at least three feed holes is required before the first and after the last component.
- 8. Splices will not interfere with the sprocket feed holes.

ORDERING & SHIPPING INFORMATION: MCR22 Series packaging options, Device Suffix

U.S.	Europe Equivalent	Shipping	Description of TO92 Tape Orientation
MCR22-6,8 MCR22-6RLRA MCR22-6RLRP	MCR22–8RL1 MCR22–8ZL1	Radial Tape and Reel (2K/Reel) Bulk in Box (5K/Box) Radial Tape and Reel (2K/Reel) Radial Tape and Fan Fold Box (2K/Box) Radial Tape and Fan Fold Box (2K/Box)	Flat side of TO92 and adhesive tape visible N/A, Bulk Round side of TO92 and adhesive tape visible Round side of TO92 and adhesive tape visible Flat side of TO92 and adhesive tape visible

PACKAGE DIMENSIONS

TO-92 (TO-226AA) CASE 029-11 **ISSUE AJ**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

STYLE 10:

PIN 1. CATHODE 2. GATE 3. ANODE

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MCR22-6/D